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# Effect of Y<sub>2</sub>O<sub>3</sub> addition on the microstructure and density of AgSnO<sub>2</sub> contact material

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AgSnO<sub>2</sub>- $Y_2O_3$  compound powders were prepared by a mechanical alloying (MA) method, AgSnO<sub>2</sub>- $Y_2O_3$  contact material was fabricated by pressing, sintering, repressing and resintering, the effect of  $Y_2O_3$  addition, repressing and resintering on the microstructure and density of AgSnO<sub>2</sub> contact material was investigated. The results show that there are drastic dedensifications or swelling, cracks and pores in AgSnO<sub>2</sub> contact material fabricated by powder metallurgy, which thus has a lower density. The addition of  $Y_2O_3$  is helpful in improving the microstructure and density significantly. The density increases significantly after repressing and resintering, and can reach 8.42 g/cm<sup>3</sup>.

Key words: Mechanical alloying (MA), AgSnO2 contact material, Repressing, Resintering, Density.

## Introduction

With increasing requirements for the miniaturization, long lifetime, high reliability of low voltage electrical apparatus and ecological protection, conventional AgCdO materials have been gradually restricted because of their damage to the environment and human health in the manufacturing process and in service [1-4]. Hence, many investigations have been made to replace AgCdO contact materials and the literatures published show that AgSnO<sub>2</sub> contact materials have excellent electrical properties, which are comparable to those of AgCdO contact materials [5-7]. However, it was also found that the contact resistance and temperature increase of AgSnO2 are higher than those of AgCdO materials under the same conditions because silver and SnO<sub>2</sub> can be separated easily during the process of arc erosion and SnO<sub>2</sub> will aggregate on the surface of contacts, the anti-arc-erosion of AgSnO<sub>2</sub> is lower in the AC3 operation condition and AgSnO<sub>2</sub> materials are difficult to machine due to the higher hardness of  $SnO_2$  [8-10], much research has been made to tackle these problems and it is reported that trace additives can improve the workability and electrical properties of AgSnO<sub>2</sub> materials [11, 12]. In order to further understand the role of trace additives in the AgSnO<sub>2</sub> materials, the effect of trace Y2O3 additions and repressing and resintering on the density and microstructure is investigated.

## **Experimental Procedure**

The sample chemical compositions were 90 wt%Ag/

10 wt%SnO2 and 90 wt%Ag/9 wt%SnO2/1 wt%Y2O3. A mechanical alloying method was adopted to prepare AgSnO<sub>2</sub> and AgSnO<sub>2</sub>-Y<sub>2</sub>O<sub>3</sub> compound powders. These powders were milled together in a vibrating mill under argon gas, and the rotating velocity, milling time and the ratio of milling ball mass to powder mass were 400 rpm, 60 h and 60/1 respectively. The powders were examined with a JSM-6700F scanning electron microscope. Specimens were formed using a common mould stamping method, the total pressure of forming was 700 MPa and the dimensions of specimens were  $\Phi 20 \text{ mm} \times 5 \text{ mm}$ . The specimens were sintered at 700 °C for 4 h and then repressed at 300 MPa and resintered at 700 °C for 1 h. The microstructures of specimens were observed using an OLYMPUS GX71 optical microscope. The density of the samples was tested according to Archimede's law.

#### **Results and Discussion**

#### Morphology of AgSnO<sub>2</sub> powder

Fig. 1(a) and Fig. 1(b) are SEM micrographs of the  $AgSnO_2$  compound powder at low and high magnification respectively. It can be seen from Fig. 1 (a) that the powder



Fig. 1. SEM micrographs of  $AgSnO_2$  compound powder milled for 60 h at low and high magnification. (a) low magnification (b) high magnification.

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Fig. 2. Macrograph of AgSnO<sub>2</sub> material sintered at 700°C for 4 h.

milled for 60 h is very fine and has little aggregation, while Fig. 1 (b) shows that the powder has a uniform size and good dispersion.

#### Macrograph of sample

Fig. 2 is a macrograph of AgSnO<sub>2</sub> material sintered at 700 °C for 4 h. After sintering, there are large amounts of pores and swelling, and there are tiny pores and cracks on the side. Because AgSnO<sub>2</sub> compound powders absorb a large quantity of gas in the process of mechanical alloying, this results in poor sintering. Gases absorbed in the powders can not escape during the sintering process; subsequently cause pores and swelling or dedensification.

The radial and axial expansion ratio and densities of samples are given in Table 1. It can be seen that the radial and axial expansion ratios of AgSnO<sub>2</sub> material are much larger than those of the AgSnO<sub>2</sub>-Y<sub>2</sub>O<sub>3</sub> material, the sintering density of AgSnO<sub>2</sub> material without a Y<sub>2</sub>O<sub>3</sub> addition is only 3.48 g/cm<sup>3</sup>. However, the density of AgSnO<sub>2</sub> material with a Y<sub>2</sub>O<sub>3</sub> addition increases by 45.5%, and can reach 6.38 g/cm<sup>3</sup>. This indicates that there is an affinity between Y<sub>2</sub>O<sub>3</sub> and silver, which is beneficial to the sintering densification of silver and SnO<sub>2</sub> powders giving a higher density.

#### Microstructure of sintered samples

Fig. 3(a) and Fig. 3(b) are the microstructures of  $AgSnO_2$ and  $AgSnO_2$ - $Y_2O_3$  materials sintered at 700 °C and held for 4 h respectively. The black area is the silver matrix, while the white area is the  $SnO_2$  phase. It can be

Table 1. The effect of a  $Y_2O_3$  addition on the sintering property of  $AgSnO_2$  compound powders.

	Axial expansion ratio (%)	radial expansion ratio (%)	density (g/cm <sup>3</sup> )
$AgSnO_2$	40.0	10.0	3.48
AgSnO <sub>2</sub> -Y <sub>2</sub> O <sub>3</sub>	22.0	5.2	6.38



Fig. 3. Microstructure of  $AgSnO_2$  and  $AgSnO_2$ - $Y_2O_3$  materials sintered at 700°C and held for 4 h. (a)  $AgSnO_2$  material, (b)  $AgSnO_2$ - $Y_2O_3$  material

seen from Fig. 3(a) that white  $\text{SnO}_2$  particles aggregate in large areas, and there are some defects such as pores and cracks. From Fig. 3(b) it may be seen that fine  $\text{SnO}_2$  and  $\text{Y}_2\text{O}_3$  particles are distributed uniformly in the silver matrix, the aggregation of  $\text{SnO}_2$ ,  $\text{Y}_2\text{O}_3$  particles and silver is almost eliminated and the pores are decreased significantly. The analysis of the microstructures of the  $\text{AgSnO}_2$ - $\text{Y}_2\text{O}_3$  material further reveals that there is an affinity between  $\text{Y}_2\text{O}_3$  and silver, which favors the sintering densification of  $\text{AgSnO}_2$ - $\text{Y}_2\text{O}_3$  material.

# Effect of repressing and resintering on density and microstructure

The density of AgSnO<sub>2</sub>-Y<sub>2</sub>O<sub>3</sub> material after repressing at 300 MPa and resintering at 700 °C for 1 h is 8.42 g/cm<sup>3</sup>. This has increased approximately 32% in comparison with that without repressing and resintering. The microstructure of AgSnO<sub>2</sub>-Y<sub>2</sub>O<sub>3</sub> material after repressing and resintering is shown in Fig. 4. It can be seen that the particles of Ag,  $SnO_2$  and  $Y_2O_3$  become much finer,  $SnO_2$  and  $Y_2O_3$ particles are dispersed in the silver matrix uniformly, and there are less pores and cracks, this results in a dense structure and a higher density. The reasons why repressing and resintering can increase the density of  $AgSnO_2-Y_2O_3$ material are that repressing can make Ag and SnO2 particles extrude each other, the pressure can cause silver to be deformed plastically, and thus drive the SnO<sub>2</sub> particles to move and rotate. The primary aggregated SnO<sub>2</sub> particles and the original SnO<sub>2</sub> particles with a bigger size will be



Fig. 4. Microstructure of  $AgSnO_2$ - $Y_2O_3$  material after repressing at 300 MPa and resintering at 700°C for 1 h.

crushed, and these finer crushed  $SnO_2$  particles will flow under compression and be distributed more uniformly in the fine silver matrix, and resintering can make atoms diffuse creating a more microstructure. Also, repressing and resintering favor the elimination of internal defects and an increase in density.

# Conclusions

(1) A trace  $Y_2O_3$  addition can improve the sintering densification of  $AgSnO_2$  compound powders.

(2) In comparison with the microstructure after pressing and sintering, repressing and resintering can make the microstructure more uniform and finer.

(3) Repressing and resintering favor an increase of density, the density of  $AgSnO_2$ - $Y_2O_3$  contact material can reach 8.42 g/cm<sup>3</sup> after repressing and resintering.

# References

 J. Zheng, S.-L. Li, H.-X. Gao and Q.-Y. Li, Rare Metal Maters and Eng. 32[10] (2003) 829-831.

- 2. B.J. Prakash, The Inter. J. of Powder Metall., 1998, 34[4] (1998) 63-74.
- H.-Y. Liu, Y.-P. Wang and B.-J. Ding, Rare Met. Maters. and Eng. 31[2] (2002) 122-124.
- B.-Z. Wang, S.-E. Wang, H.-Z. Bai and F. Yao, J. Hebei University of Tech., 30[3] (2001) 77-81.
- L.-C. Cheng, Z.-B. Li and J.-Y. Zou, Low Voltage Apparatus, [3] (1994) 47-51.
- G.-Q. Zhang, D.-G. Deng, G.-X. Qi, J.-M. Guo and W.-M. Guan, Precious Metals, 20[4] (1999) 1-6.
- 7. E. Hetzmanseder and W. Rieder, IEEE Trans CPMT A, 19[3] (1996) 397-403.
- 8. D. Jennot and J. Pinard, IEEE Trans CPMT A, 17[1] (1994) 7-23.
- 9. D. Jennot and J. Pinard, in Proceeding of the 39th IEEE Holm Conference. on Electrical Contacts, 1993, p.51.
- H.A. Francisco and M. Myers, in Proceeding of the 44th IEEE Holm Conf. on Electrical Contacts, 1998, p.193.
- W. Bohm, N. Behrens and M. Lindmayer, in Proceedings of the 27th Holm Conf on Electrical Contacts, 1981, p.51.
- F. Hauner, D. Jeannot and K. McNeilly, in Proceeding of the 46th Holm Conference, 2000, p. 225.